


PLATING METHOD AND ITS DEVICE FOR SEMICONDUCTOR WAFER

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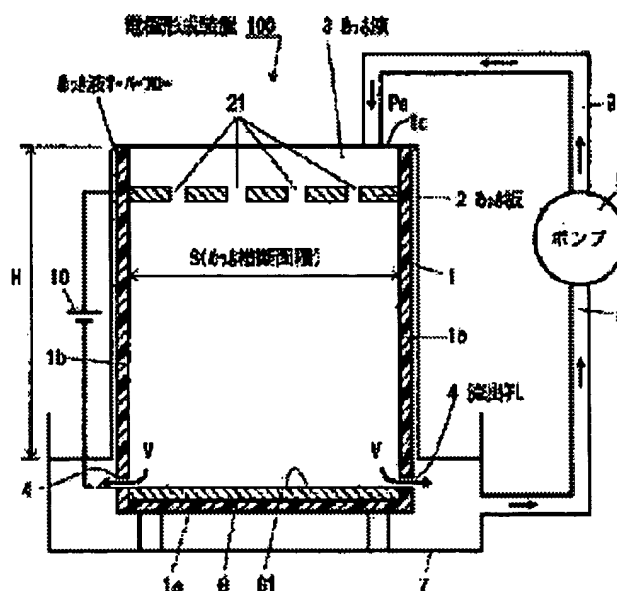
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 JP10172974 (A)

Abstract of JP10172974

PROBLEM TO BE SOLVED: To uniformly form the diameter, height and composition of a bump electrode.

SOLUTION: An almost disk-like wafer 6 as a cathode is arranged in parallel at the base part 1a of a cylindrical plating tank 1, and the side parts are approximated to the inner faces of the plating tank 1. Plural slit-like flow-out holes 4 are provided on the side parts 1b of the plating tank 1 in heights which are almost equal to the height of the upper face part 61 of the wafer 6 in a circumferential direction. A plating board 2 as a mesh-like anode, which has almost the same shape as the wafer 6 and has plural hole parts 21, is horizontally arranged on the side of an opening face part 1c by facing the wafer 6, and the side part is approximated to the inner face of the plating tank 1. Plating liquid 3 is supplied in the plating tank 1 and a part overflows from the opening face part 1c. A water tank 7 is arranged below the plating tank 1 and plating liquid 3 flowing out from the flow-out holes 4, and the opening face part 1c is accumulated. The plating liquid 3 is drawn by a pump 5, it passes through pipes 8 and 9 and it is circularly supplied to the tank 1 from the opening face part 1c.



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